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[Vishay/Siliconix](#)
[SI1028X-T1-GE3](#)

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Dual N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY			
V _{DS} (V)	R _{DS(on)} (Ω) Max.	I _D (A)	Q _g (Typ.)
30	0.650 at V _{GS} = 10 V	0.48	0.5
	0.770 at V _{GS} = 4.5 V	0.45	

FEATURES

- TrenchFET[®] Power MOSFET
- ESD Protected: 550 V Typical HBM
- Material categorization:
 For definitions of compliance please see www.vishay.com/doc?99912



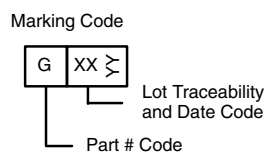
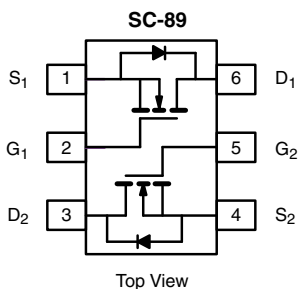
RoHS
 COMPLIANT
 HALOGEN
FREE

BENEFITS

- Low Offset Voltage
- Low-Voltage Operation
- High-Speed Circuits
- Small Board Area

APPLICATIONS

- Load/Signal Switching for Portable Devices
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems



Ordering Information: Si1028X-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)				
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	V	
Gate-Source Voltage	V _{GS}	± 20		
Continuous Drain Current (T _J = 150 °C) ^a	I _D	T _A = 25 °C	A	
		T _A = 70 °C		
Pulsed Drain Current (t = 300 μs)	I _{DM}	1		
Continuous Source-Drain Diode Current	I _S	T _A = 25 °C	A	
		T _A = 70 °C		
Maximum Power Dissipation ^a	P _D	T _A = 25 °C	W	
		T _A = 70 °C		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typ.	Max.	Unit	
Maximum Junction-to-Ambient ^b	R _{thJA}	t ≤ 5 s	470	565	°C/W
		Steady State	560	675	

Notes:

- Surface mounted on 1" x 1" FR4 board.
- t = 5 s.

Si1028X

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SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	30			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = 250 μA		33		mV/°C
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			-2.8		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1		2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 20	μA
		V _{DS} = 0 V, V _{GS} = ± 4.5 V			± 1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1	
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 85 °C			10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	1			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 0.5 A		0.540	0.650	Ω
		V _{GS} = 4.5 V, I _D = 0.2 A		0.640	0.770	
Forward Transconductance	g _{fs}	V _{DS} = 10 V, I _D = 0.5 A		1		S
Dynamic^b						
Input Capacitance	C _{iss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		16		pF
Output Capacitance	C _{oss}			8		
Reverse Transfer Capacitance	C _{rss}			4		
Total Gate Charge	Q _g	V _{DS} = 15 V, V _{GS} = 10 V, I _D = 0.5 A		1	2	nC
				0.5	1	
Gate-Source Charge	Q _{gs}	V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 0.5 A		0.15		
Gate-Drain Charge	Q _{gd}			0.20		
Gate Resistance	R _g	f = 1 MHz		50		Ω
Turn-On Delay Time	t _{d(on)}	V _{DD} = 15 V, R _L = 37.5 Ω I _D = 0.38 A, V _{GEN} = 4.5 V, R _g = 1 Ω		8	16	ns
Rise Time	t _r			10	20	
Turn-Off Delay Time	t _{d(off)}			9	18	
Fall Time	t _f			8	16	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 15 V, R _L = 37.5 Ω I _D = 0.38 A, V _{GEN} = 10 V, R _g = 1 Ω		2	4	
Rise Time	t _r			9	18	
Turn-Off Delay Time	t _{d(off)}			7	14	
Fall Time	t _f			8	16	
Drain-Source Body Diode Characteristics						
Pulse Diode Forward Current ^a	I _{SM}				1	A
Body Diode Voltage	V _{SD}	I _S = 0.38 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = 0.38 A, di/dt = 100 A/μs		9	18	ns
Body Diode Reverse Recovery Charge	Q _{rr}			2	4	nC
Reverse Recovery Fall Time	t _a			5		ns
Reverse Recovery Rise Time	t _b			4		

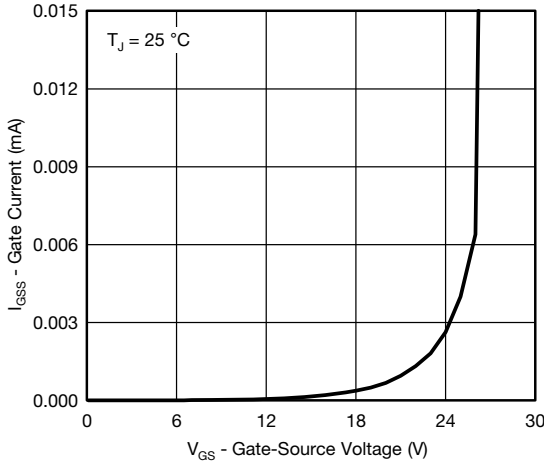
Notes:

- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %.
- b. Guaranteed by design, not subject to production testing.

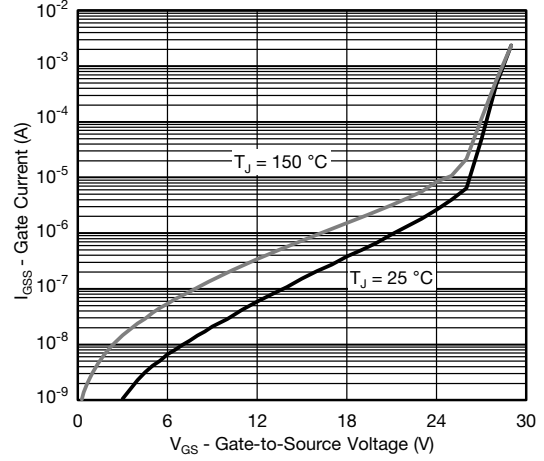
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



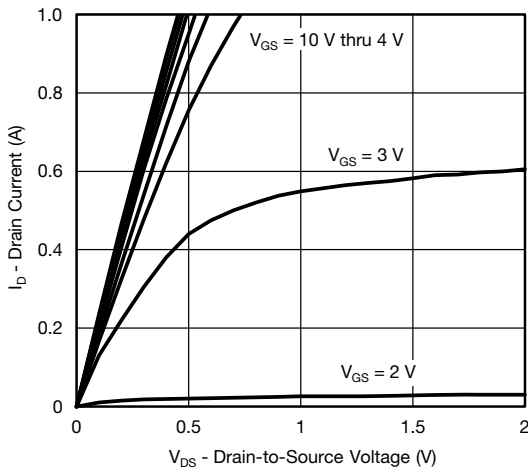
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



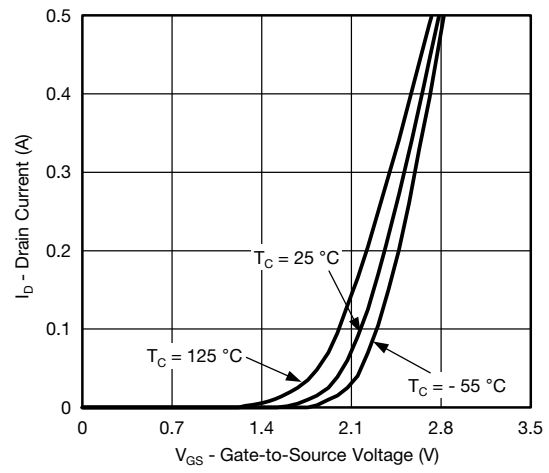
Gate Current vs. Gate-Source Voltage



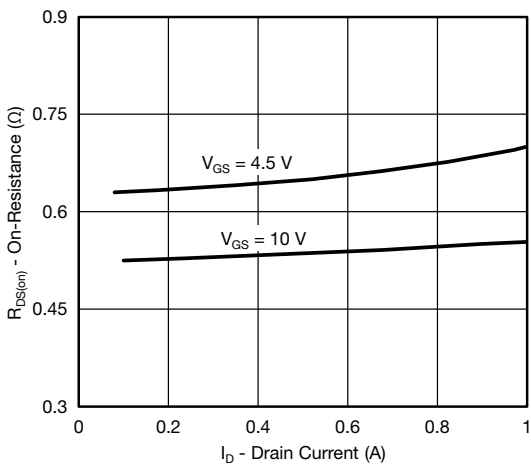
Gate Current vs. Gate-Source Voltage



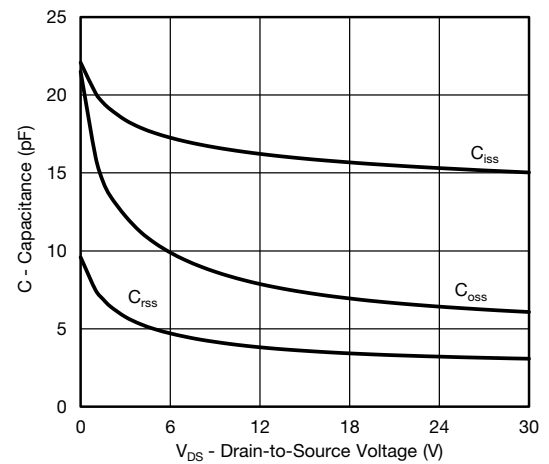
Output Characteristics



Transfer Characteristics



On-Resistance vs. Drain Current



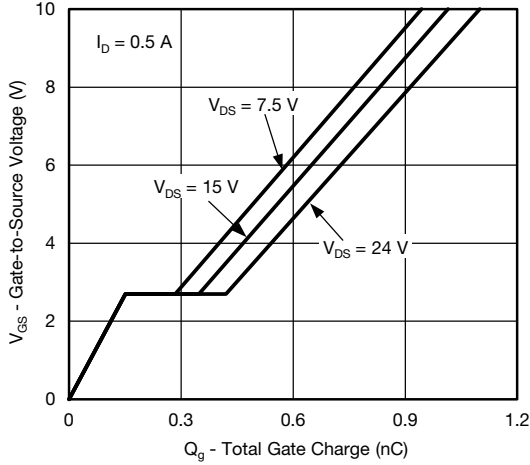
Capacitance

Si1028X

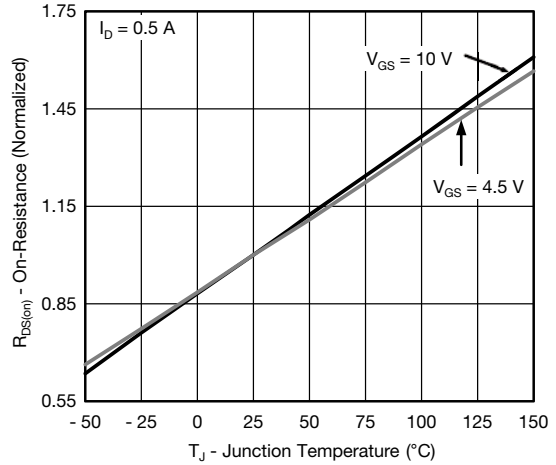
Vishay Siliconix



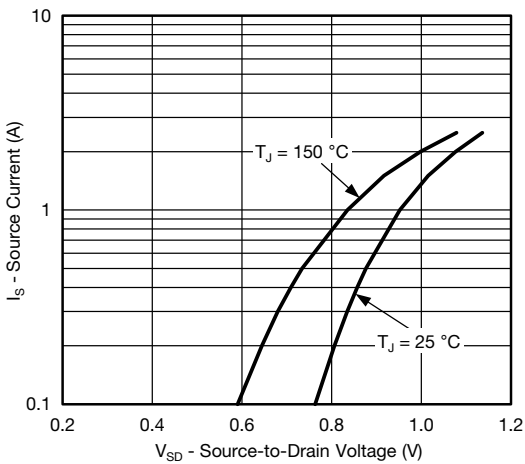
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



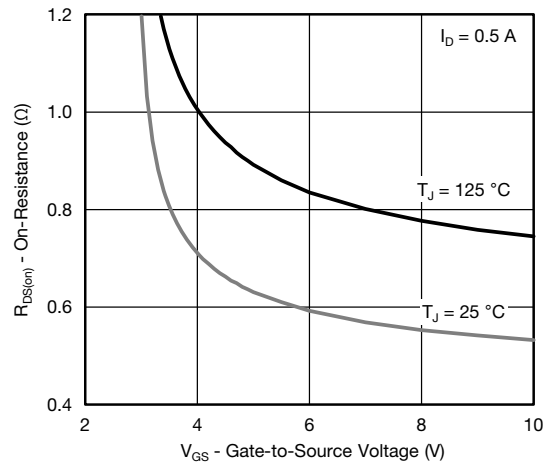
Gate Charge



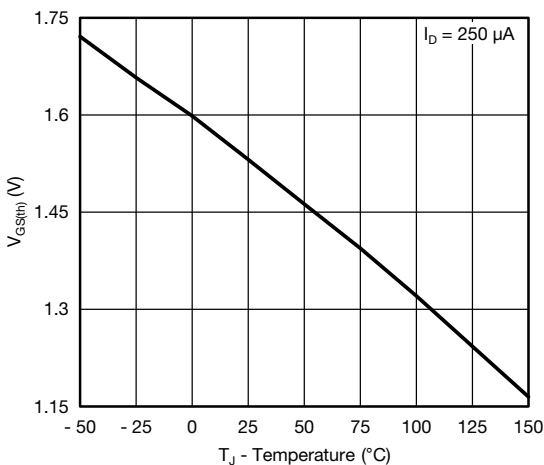
On-Resistance vs. Junction Temperature



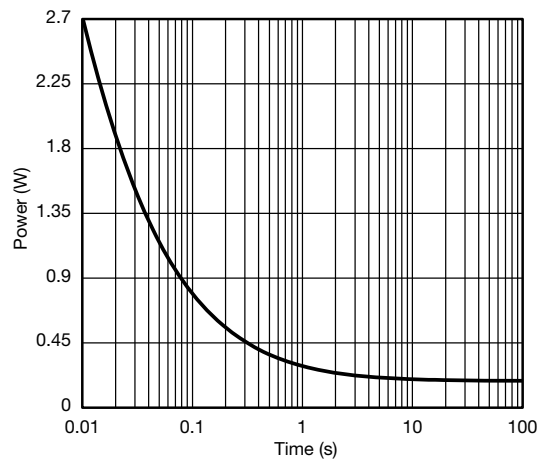
Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

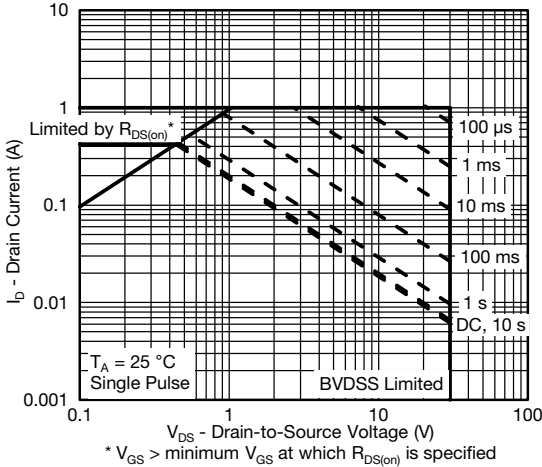


Single Pulse Power, Junction-to-Ambient

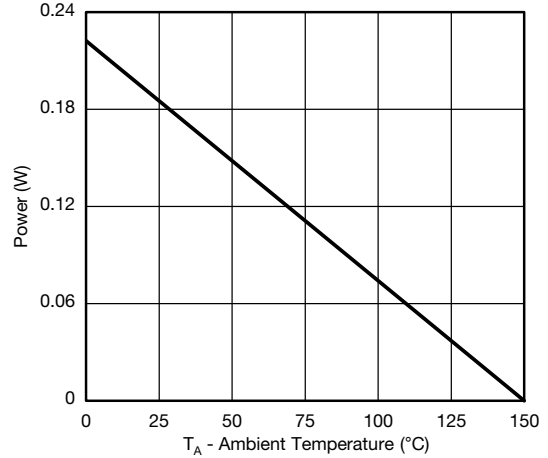


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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

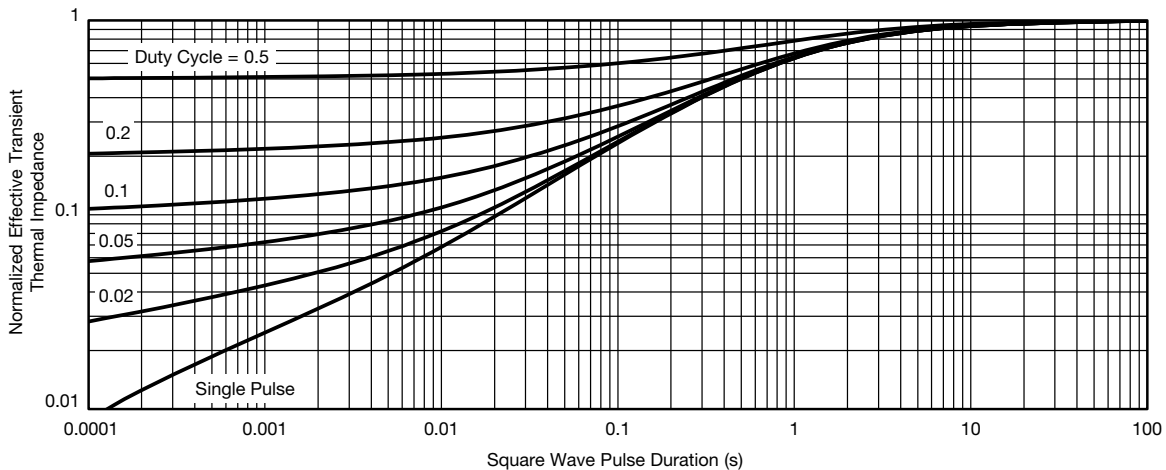


Safe Operating Area, Junction-to-Ambient



Power Derating, Junction-to-Ambient

* The power dissipation P_D is based on $T_{J(max)} = 150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

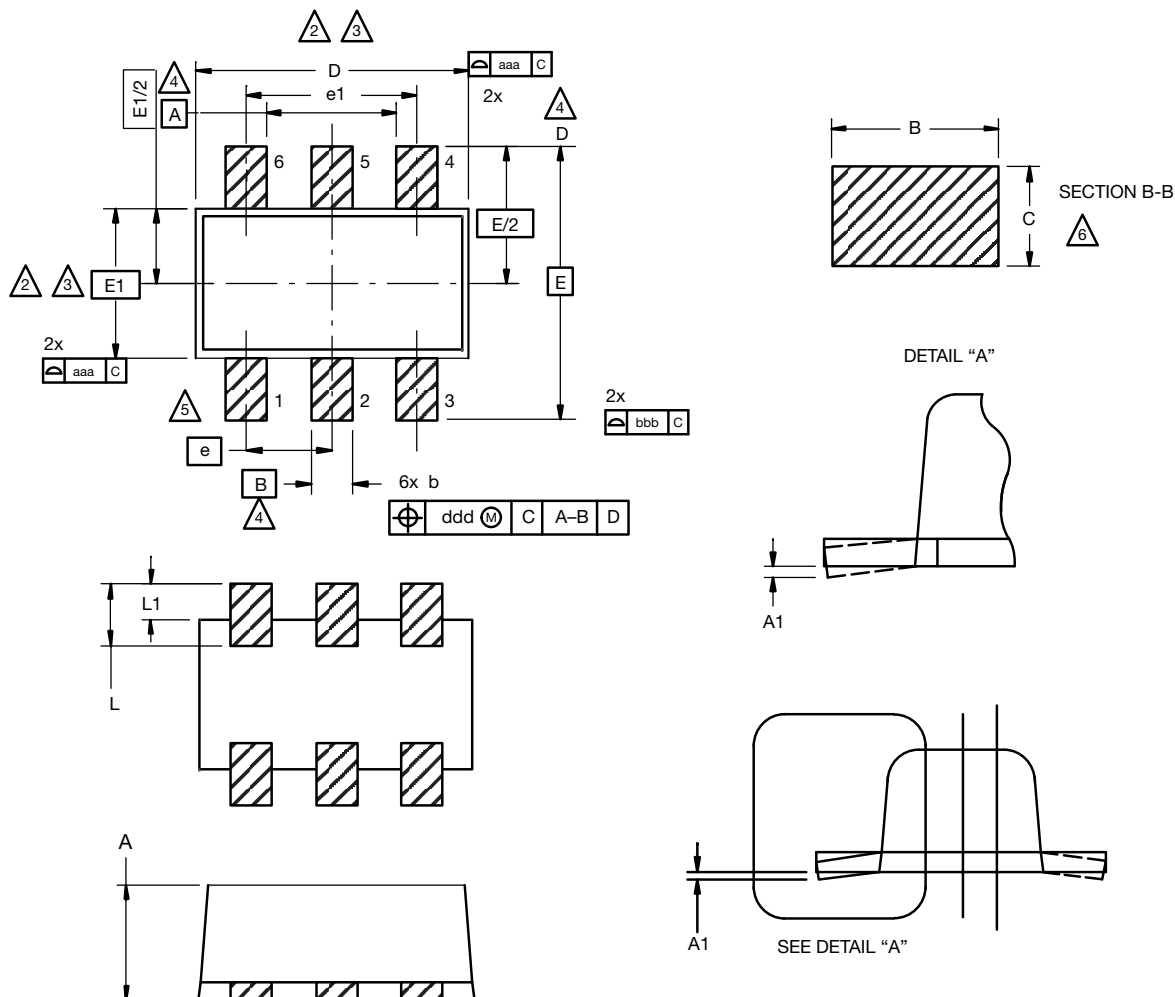


Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppq?63862.



SC-89 6-Leads (SOT-563F)



Notes

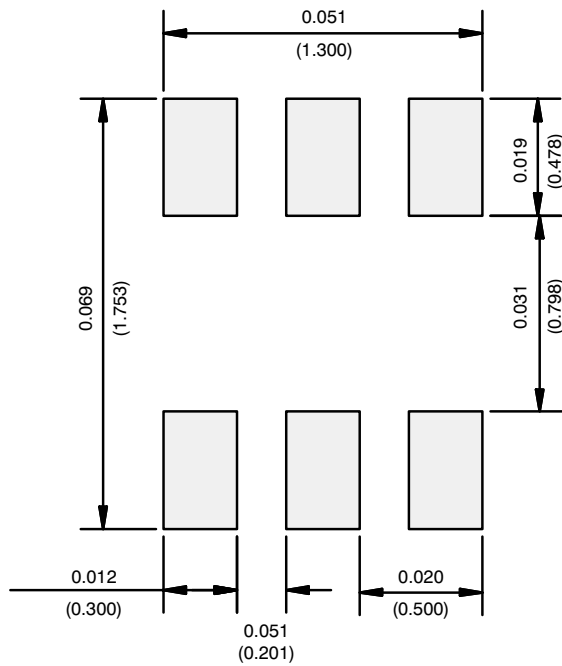
1. Dimensions in millimeters.
- ② Dimension D does not include mold flash, protrusions or gate burrs. Mold flush, protrusions or gate burrs shall not exceed 0.15 mm per dimension E1 does not include interlead flash or protrusion, interlead flash or protrusion shall not exceed 0.15 mm per side.
- ③ Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, the bar burrs, gate burrs and interlead flash, but including any mismatch between the top and the bottom of the plastic body.
- ④ Datums A, B and D to be determined 0.10 mm from the lead tip.
- ⑤ Terminal numbers are shown for reference only.
- ⑥ These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.56	0.58	0.60
A1	0	0.02	0.10
b	0.15	0.22	0.30
c	0.10	0.14	0.18
D	1.50	1.60	1.70
E	1.50	1.60	1.70
E1	1.15	1.20	1.25
e	0.45	0.50	0.55
e1	0.95	1.00	1.05
L	0.25	0.35	0.50
L1	0.10	0.20	0.30

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DWG: 5880



RECOMMENDED MINIMUM PADS FOR SC-89: 6-Lead



Recommended Minimum Pads
 Dimensions in Inches/(mm)

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